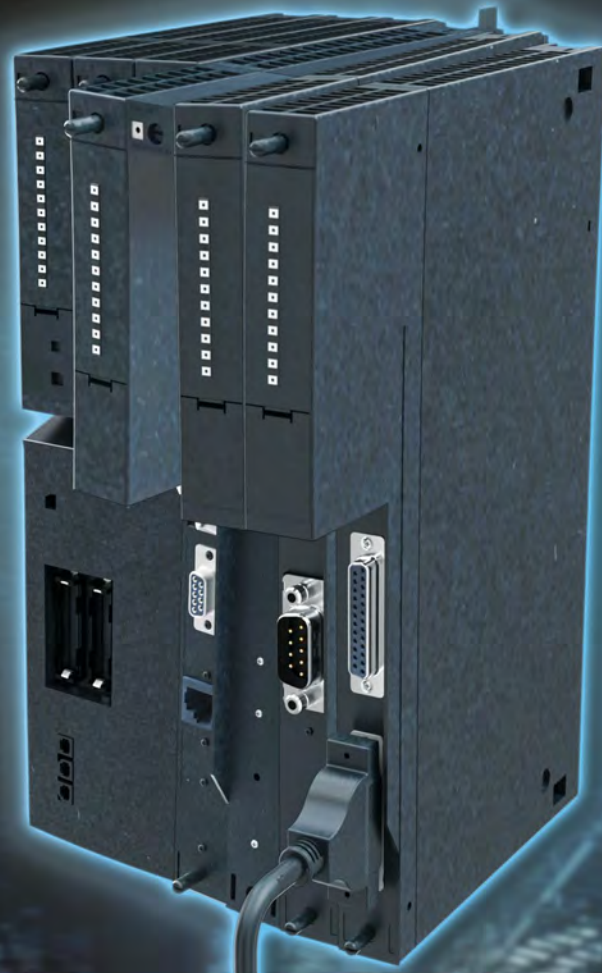
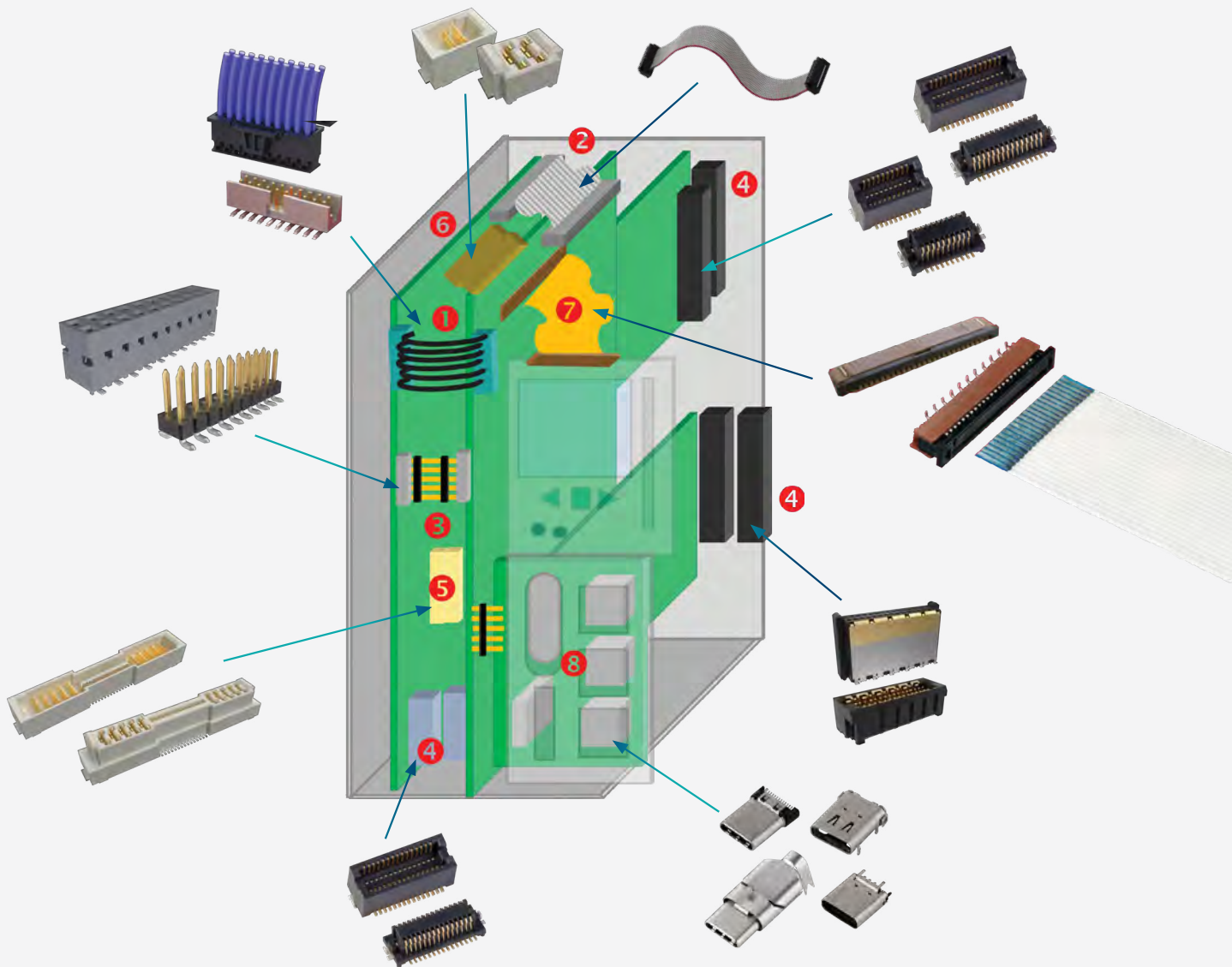


Interconnect solutions for PLC

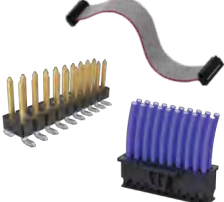







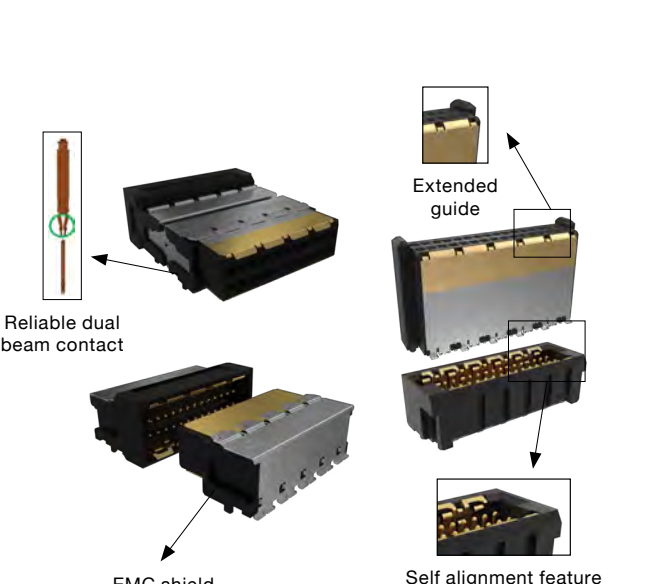
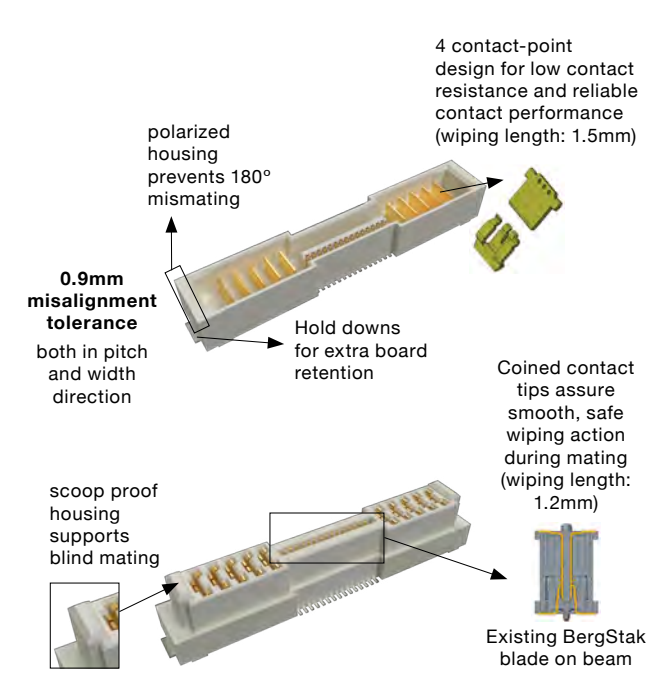


From modular to integrated PLCs, Amphenol provides innovative solutions that meet the challenges of PLC design engineers



- | | | | |
|---|---|--|---|
| <p>1</p> <p>Wire to Board – Signal:
Dubox® 2.54mm
Minitek® 2.00mm</p> | <p>2</p> <p>Ribbon Cable to Board:
Minitek® 2.00mm</p> | <p>3</p> <p>Board to Board – Pin on Socket:
Dubox® 2.54mm
BergStik® 2.54mm
Minitek® 2.00mm</p> | <p>4</p> <p>Board to Board – Mezzanine:
BergStak® 0.50mm
Conan® 1.00mm
Minitek® MicroSpeed 1.00mm</p> |
| <p>5</p> <p>Board to Board – Hybrid:
ComboStak® 0.80 / 2.00mm</p> | <p>6</p> <p>Board to Board – Power:
PowerStak® 2.00mm</p> | <p>7</p> <p>FPC to Board:
FFC/FPC 0.50 – 1.00mm</p> | <p>8</p> <p>Input Output:
USB</p> |

Programmable Logic Control – Focus Products

 <ul style="list-style-type: none"> • Pitch 2.00mm • Current Rating: 2 A • Modular System 	 <ul style="list-style-type: none"> • Pitch 0.50 / 1.00mm • ZIF, Non-ZIF • Top, Bottom, Vertical contacts 	 <ul style="list-style-type: none"> • Pitch 2.00 (P) 0.80mm (S) • Current Rating: 20 A (P) 0.8 A (S) • Speed: 12 Gb/s 	 <ul style="list-style-type: none"> • Pitch 0.50mm • Current Rating: 0.5 A • Stack height: 3.0 to 6.0mm
 <ul style="list-style-type: none"> • Pitch: 1.00mm • Current Rating: 1 A • Speed: up to 8Gb/s 	 <ul style="list-style-type: none"> • Pitch: 1.00mm • Current Rating: 1 A • Speed: 25 Gb/s, EMI shielding 	 <ul style="list-style-type: none"> • USB C, USB 2.0 • Speed: 20 Gb/s • Cable Assemblies solutions 	<p>BergStik® Dubox®</p>  <ul style="list-style-type: none"> • Pitch 2.54mm • Current Rating: 3 A • Modular System
<p>Minitek® MicroSpeed</p>  <ul style="list-style-type: none"> Reliable dual beam contact EMC shield Extended guide Self alignment feature 		<p>ComboStak® 2.00mm / 0.80mm</p>  <ul style="list-style-type: none"> 0.9mm misalignment tolerance both in pitch and width direction polarized housing prevents 180° mismatching Hold downs for extra board retention 4 contact-point design for low contact resistance and reliable contact performance (wiping length: 1.5mm) scoop proof housing supports blind mating Coined contact tips assure smooth, safe wiping action during mating (wiping length: 1.2mm) Existing BergStak blade on beam contact system 	

R&D Sites & Manufacturing Footprint

Besançon, France

Nantong, China

Senai, Malaysia

FCI Basics, the Amphenol PCB interconnect specialist

BASICS

The brand BASICS was established at Amphenol in the early 2000s, when a portfolio of industry leading Wire-to-Board and Board-to-Board connectors was brought together in a global Amphenol business unit. With industry recognized brand names like Dubox®, BergStik®, Quickie®, Minitek® and BergStak®, BASICS has developed itself into a global leader in PCB interconnect.

EXPANDED PRODUCT RANGE

Today, BASICS offers a broad, modular interconnect platform of high quality and innovative solutions for all main industries and applications. The BASICS portfolio offers the right mix between industry-proven solutions and state-of-the-art connector technology.

Our solutions include :

- Wire-to-Board
- Board-to-Board
- Input/output
- FFC/FPC
- Hybrid Wire-to-Board
- Cable assembly
- Hybrid Board-to-Board
- Customized solutions



Modular & Flexible Product Range

With millions of configurable options, we have the products to meet your performance and quality requirements for your specific application.



In Stock

Our global and regional distribution partners are stocking the most popular connectors for your designs, with over 6,000 products ready to ship.



Easy Design-In

Instant online access to all related info, a fast Sample Service, crimped leads and stocked items: it's very easy to complete your design with BASICS!



Customized Solutions

Partner with us for your customized connection needs. With advanced engineering and fast prototyping, we provide solution proposals in a week or less.